

Title (en)  
METHOD FOR PRODUCING ALUMINUM ALLOY THICK PLATE

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINER DICKEN PLATTE AUS EINER ALUMINIUMLEGIERUNG

Title (fr)  
PROCÉDÉ DE FABRICATION D'UNE PLAQUE ÉPAISSE D'ALLIAGE D'ALUMINIUM

Publication  
**EP 2130931 A1 20091209 (EN)**

Application  
**EP 08722912 A 20080327**

Priority  

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- JP 2007095419 A 20070330
- JP 2007095423 A 20070330
- JP 2007098495 A 20070404

Abstract (en)  
Disclosed is a method for manufacturing an aluminum alloy thick plate. The method includes, in the following order, a melting step (S1) for melting an aluminum alloy, the aluminum alloy containing a predetermined amount of Mg and further containing at least one of Si, Fe, Cu, Mn, Cr, Zn, Ti, and Zr, with the remainder being aluminum and inevitable impurities; a hydrogen gas removal step (S2) for removing hydrogen gas from the molten aluminum alloy; a filtration step (S3) for removing inclusions from the aluminum alloy from which hydrogen gas have been removed; a casting step (S4) for casting the aluminum alloy, from which inclusions have been removed, into a slab; a slicing step (S5) for slicing the slab into an aluminum alloy thick plate having a predetermined thickness; and a heat treatment step (S6) for subjecting the aluminum alloy thick plate having a predetermined thickness to a heat treatment by holding the same at a temperature of 400°C or higher but lower than its melting point for one hour or longer.

IPC 8 full level  
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